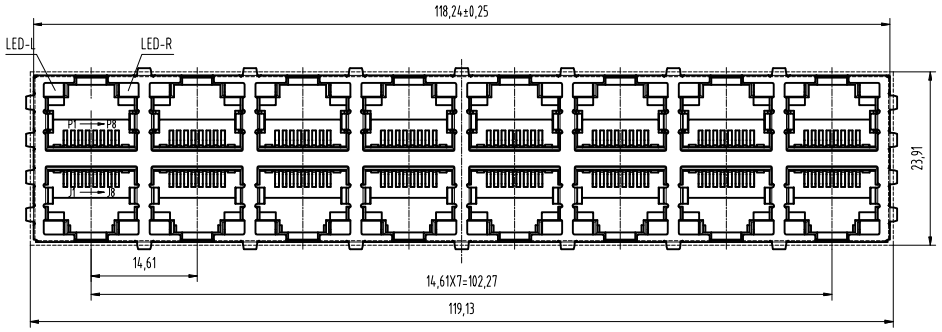
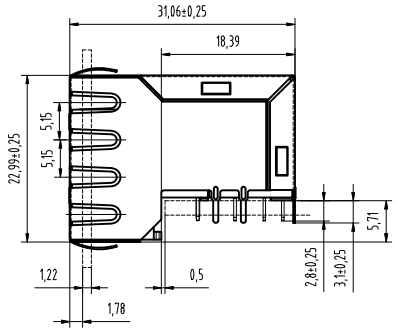
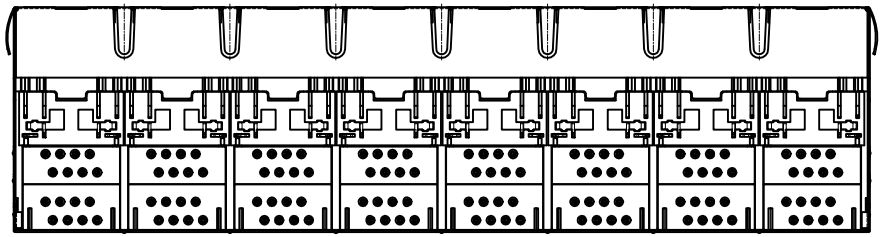


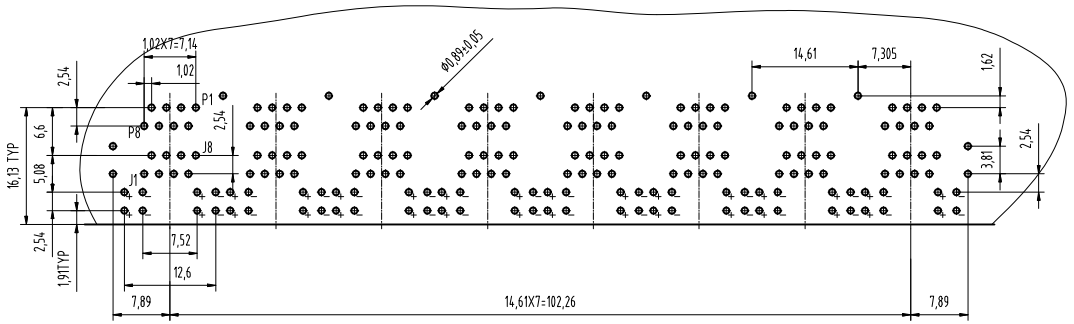


1. MATERIALS :
   - 1.1 INSULATOR: THERMOPLASTIC, BLACK, UL 94V-0
   - 1.2 SHIELD: COPPER ALLOY
   - 1.3 RJ MATING CONTACT: PHOSPHOR BRONZE
   - 1.4 RJ SOLDER TAIL: COPPER ALLOY
2. FINISH :
   - 2.1 SHIELD: 50u" Min. NICKEL PLATED OVERALL
   - 2.2 CONTACT: SELECTIVE GOLD PLATED (SEE ORDER INFORMATION) IN CONTACT AREA, 80u" Min. TIN PLATED IN SOLDER AREA, 30u" Min. NICKEL UNDERPLATED OVERALL.
3. ELECTRICAL CHARACTERISTICS
   - 3.1 INSULATION RESISTANCE: 500MΩ MIN.
   - 3.2 OPERATING TEMPERATURE: -40°C ~ +105°C.
4. NOTES:
   - 4.1 THIS COMPONENT AND ITS HOMOGENEOUS SUBCOMPONENTS ARE RoHS COMPLIANT.
   - 4.2 RESISTANCE TO SOLDERING HEAT: 265°C FOR 5 SECONDS, AND ONLY FOR WAVE SOLDERING PROCESS.
5. **ORDER INFORMATION:**

RJ31M32AB2 SX -88B

CONTACT PLATED:
S1: GOLD FLASH
S2: 3u" GOLD
S3: 5u" GOLD
S4: 10u" GOLD
S5: 15u" GOLD
S6: 30u" GOLD
S7: 50u" GOLD





RECOMMENDED PCB LAYOUT(PCB THICKNESS: 1.6mm)
COMPONENT SIDE VIEW(TOLERANCE: ±0.05)

PRELIMINARY
Subject to Change without notice

REV.	DESCRIPTION	ECN NO.	NAME	DATE
A1	NEW RELEASE		Milo	Mar.25.2011

REVISIONS

DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15
GENERAL ANGLE:	±3°

TITLE: RJ45 8P8C 2*8 PORT WITH LED R/A DIP TYPE

DWG. NO.: C-RJ31M32AB2SX-88B

DRAWN: Milo

PART NO.: **XMD-RJ31M32AB2SX-88B**

CHECKED: Karen

APPROVED: Frank

UNIT:	SCALE:	SHEET:	DWG. SIZE:	LAYER:
mm	none	1 OF 1	A4	CR097

RFQ NO.: Q1103XXX

Xmultiple

ARTICLE: CPC-CN-002-C